

## Product features

High precision machining technology

Low temperature drift, high power.

Ceramic substrate, 50  $\Omega$  coplanar waveguide

Gold wire bonding

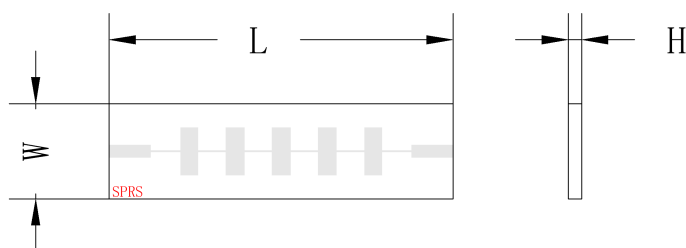
## Tech specifications

| Items              | Parameters    | Units |
|--------------------|---------------|-------|
| Center Frequency   | 1.5           | GHz   |
| Bandwidth          | DC-3.0        | GHz   |
| Passband IL        | 2.0           | dB    |
| Ripple             | 2.0           | dB    |
| VSWR               | 1.5:1         |       |
| Group delay ripple | 0.4           | ns    |
| Rejection          | 55@4.5-7.5GHz | dBc   |
| Rejection          | 30@7.5-9.2GHz | dBc   |

## Other requirement (Design assurance)

|                 |                      |
|-----------------|----------------------|
| power           | 0.5W CW              |
| Operation Temp. | -55~+85°C            |
| Storage Temp.   | -55~+125°C           |
| Outline size    | L:4.5, W:4.5, h:0.26 |

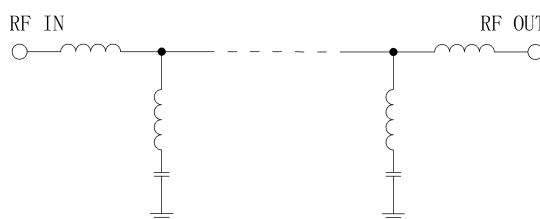
## Outline drawing: Port centered



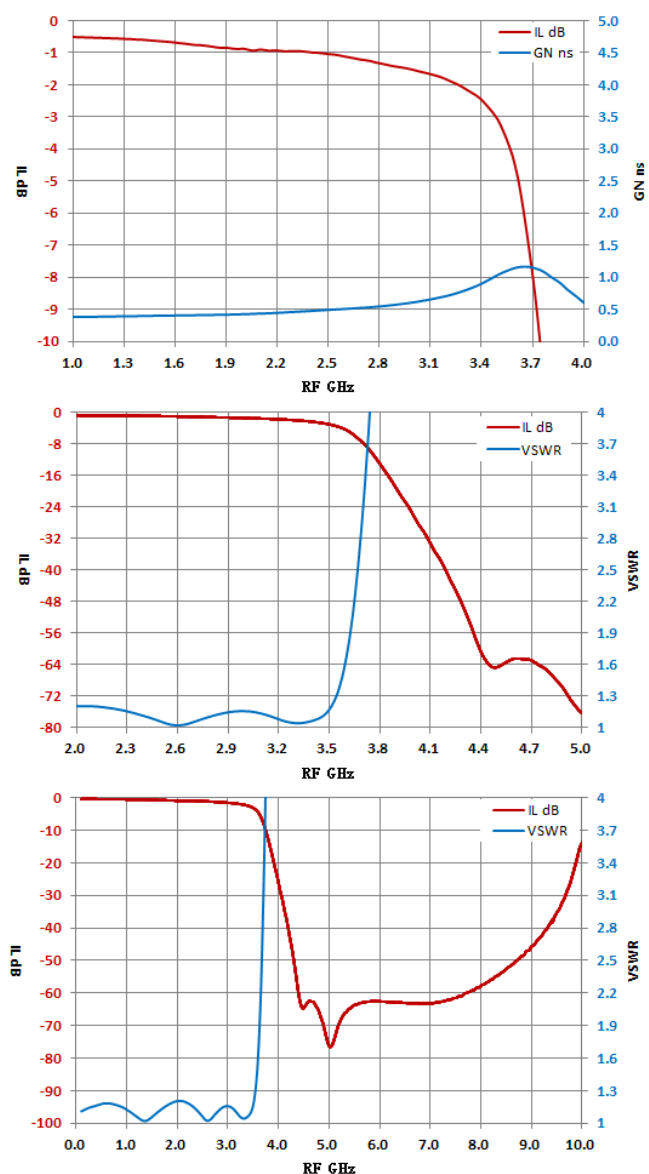
## Reference picture



## Schematic diagram

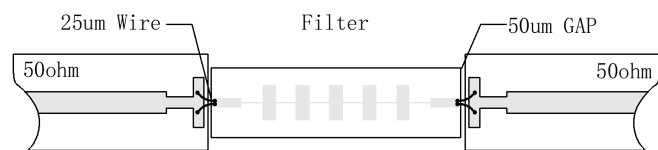


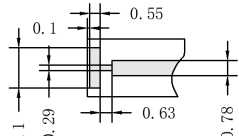
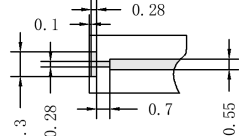
## Typical test curve



Note: The specifications and performance data contained in this data sheet are based on tests established by COM-MW.

## Suggested PCB Layout



| PCB Rogers5880, h:0.254mm                                                                                                             | PCB Rogers4350B, h:0.254mm                                                                                                           |
|---------------------------------------------------------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------|
|  <p>Dimensions: 0.1, 0.55, 0.29, 0.63, 0.78, 2.1</p> |  <p>Dimensions: 0.1, 0.28, 0.28, 0.7, 0.55, 1.3</p> |

## Note

- 1: The chip is recommended to be used in separate chambers, with one side 0.1mm away from the side wall and the surface 1.74mm away from the top cover. The ports are interchangeable;
- 2: Suggest using conductive adhesive for bonding;
- 3: 芯片应安装在可伐(推荐) 或铜等与陶瓷热膨胀系数(6.7ppm/C)相近的材料, 载体厚度 $\geq 0.2\text{mm}$ ;
- 4: Suggest using a T-shaped structure for microstrip bonding.